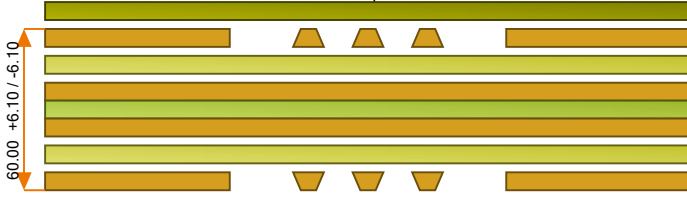


Layer	Stack up	Supplier Description	Description	εr	Copper Layer Type	Copper Coverage	Processed Thickness	Base Thickness	
1	60.00 +6.10 / -6.10 Top 	PSR-4000 BN (DG)	Liquid PhotoImageable Mask	3.900			1.000		
		ED Copper Foil	TWS		Mixed	30.000	1.378	1.378	
		185HR 2113	2113	4.060			4.178	4.213	
2		VT-47 6-7628	6-7628	4.220	Plane	70.000	0.700	0.700	
3					Plane	70.000	45.000	45.000	
4		185HR 2113	2113	4.060			0.700	0.700	
4	Bot 	ED Copper Foil	TWS		Mixed	30.000	1.378	1.378	
		PSR-4000 BN (DG)	Liquid PhotoImageable Mask	3.900			1.000		

Impedance Signal Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Target Impedance	Calculated Impedance	Structure Image	Structure Name	CI Notes-1
1	7.000	0.000	0.000	2	0	50.000	49.130		Coated Microstrip 1B	
1	5.500	5.000	0.000	2	0	90.000	89.940		Edge Coupled Coated Microstrip 1B	
4	7.000	0.000	0.000	3	0	50.000	49.130		Coated Microstrip 1B	
4	5.500	5.000	0.000	3	0	90.000	89.940		Edge Coupled Coated Microstrip 1B	

Notes

StackName: 4 Lyr STD	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1	
Date: 9/5/2024	Associated Documents:						
Author: Stelios Androulidakis							
Department:							
Site:							